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Sheet 1 of 2

FORM PTO-1449 (REV. 7-80)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. HIT 2 925-08	SERIAL NO. 10/671 618	
LIST OF DOCUMENTS CITED BY APPLICANT <i>(Use several sheets if necessary)</i>				APPLICANT J. TANAKA et al		
				FILING DATE 09/29/03		
U.S. PATENT DOCUMENTS						
EXAMINER INITIAL	DOCUMENT	DATE	NAME	CLASS	SUBCLASS	FILING DATE (If Appropriate)
nbe	AA	5,563,762	10/1996	Leung et al		
	AB	5,117,272	05-1992	Nomura et al		
	AC	5,310,863	05-1994	Sachdev		
	AD	6,071,755	06-2000	Baba et al		
	AE	6,106,906	08-2000	Matsuda et al		
	AF	5,296,716	03-1994	Ovashinsky et al		
	AG	4,132,823	1/2/79	Blackwell et al		
nbe	AH	6,465,827	10/2002	Tanaka et al		
	AI					
	AJ					
	AK					
FOREIGN PATENT DOCUMENTS						
	DOCUMENT	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
nbe	AL	8-124917	05-1996	Japan		<input type="checkbox"/> <input type="checkbox"/>
	AM	7-278301	10-1995	Japan		<input type="checkbox"/> <input type="checkbox"/>
	AN	07-221259	8/18/95	Japan		<input type="checkbox"/> <input type="checkbox"/>
nbe	AO	09-293837	11/11/97	Japan		<input type="checkbox"/> <input type="checkbox"/>
	AP					<input type="checkbox"/> <input type="checkbox"/>
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)						
nbe	AR	Lecture Collections in '96 Ferroelectric Film Memory Technique Forum, Science Forum, Inc., page 4-4, lines 1-12, Ishihara, January 26, 1996.				
nbe	AS	Epoxy Molding Compounds for Semiconductor Devices, Thermosetting Resins, Vol. 13, No. 4, page 37, right column, lines 8-23, Ogata et al, 1992.				
nbe	AT	Packaging Technique for Surface Mount Type LSI Packages and Improvements in Its Reliability, page 451, edited by Hitachi, Ltd.				
EXAMINER Jasmine Clark				DATE CONSIDERED 7/21/04		

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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Sheet 2 of 2

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LIST OF DOCUMENTS CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT J. TANAKA et al		GROUP 2815	
U.S. PATENT DOCUMENTS							
* EXAMINER INITIAL		DOCUMENT	DATE	NAME	CLASS	SUBCLASS	FILING DATE (If Appropriate)
	AA						
	AB						
	AC						
	AD						
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	AF						
	AG						
	AH						
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	AJ						
	AK						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
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	AM						<input type="checkbox"/> <input type="checkbox"/>
	AN						<input type="checkbox"/> <input type="checkbox"/>
	AO						<input type="checkbox"/> <input type="checkbox"/>
	AP						<input type="checkbox"/> <input type="checkbox"/>
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)							
gbe	AR	A Study of Package Cracking During the Reflow Soldering Process, "A" Edition, Vol. 55, No. 510, Kitano et al, 1989-2.					
gbe	AS	Effects of Mold Compound Properties on Lead-on-Chip (LOC) Package Reliability During IR Reflow, 1996 Electronic Components and Technology Conference, Yang et al.					
	AT						
EXAMINER Jasmine Clark				DATE CONSIDERED 7/21/04			
* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							